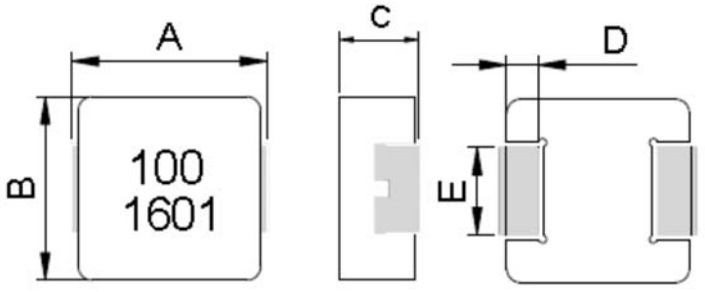
FEATRLRES

- Shielded construction.
- Capable of corresponding high frequency (5MHz).
- Low loss realized with low DCR.
- High performance (Isat) realized by metal dust core.
- Ultra low buzz noise, due to composite construction.
- 100% Lead(Pb)-Free and RoHS compliant.

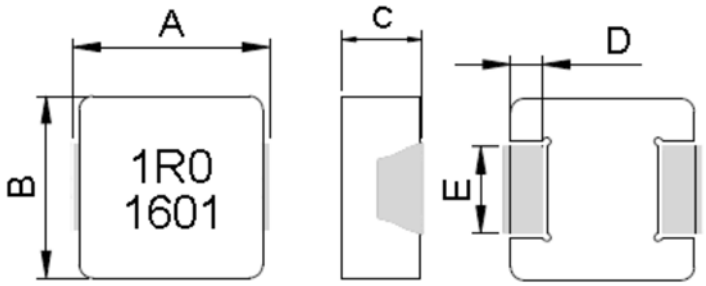
APPLICATIONS

- DC/DC converters in distributed power systems.
- DC/DC converter for Field Programmable Gate Array(FPGA).
- Battery powered devices.
- Thin type on-board power supply module for exchanger.
- VRM for server.
- High current, low profile POL converters.
- PDA/notebook/desktop/server and battery powered devices.

CONFIGRLRATIONS & DIMENSIONS (unit in mm)

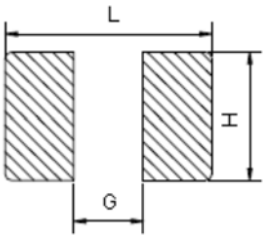


leadframe



non-leadframe

Recommended Land pattern



L	G	H
14.5	8.0	5.0

Note:
1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.15mm and above.

Type	A	B	C	D	E	Inductance
HMPL1205S	13.5±0.5	12.6±0.2	4.7±0.3	2.3±0.3	4.0±0.3	1.0uH and below
						1.5uH and above

ELECTRICAL CHARACTERISTICS

Part Number	Inductance L0 A(uH)±20%	Heat Rating Current DC I rms.(A)		Saturation Current DC I sat. (A)		DCR (mΩ)		Type
		Typ	Max	Typ	Max	Typ	Max	
HMPL1205SP-R47MN-D	0.47	38	34	65	58	0.77	0.9	non-leadframe
HMPL1205SP-R68MN-D	0.68	34	31	50	42	1.3	1.55	non-leadframe
HMPL1205SP-1R0MN-D	1.00	30	27	40	34	1.6	1.9	non-leadframe
HMPL1205SP-1R5MN-D	1.50	25	22	31	28	3.2	3.8	leadframe
HMPL1205SP-2R2MN-D	2.20	17	15.5	26	23	4.1	4.8	leadframe
HMPL1205SP-3R3MN-D	3.30	15.5	14	23	20.5	6.0	7.0	leadframe
HMPL1205SP-4R7MN-D	4.70	14	12.5	18.5	16	8.8	10.2	leadframe
HMPL1205SP-6R8MN-D	6.80	12	11	16.5	15	13	16	leadframe
HMPL1205SP-100MN-D	10.0	10	9.0	13	10.5	19.2	22	leadframe
HMPL1205SP-150MN-D	15.0	9.4	8.2	11	9.2	30	36	leadframe

Note:

1.Test frequency : Ls : 100KHz /1.0V.

2.All test data referenced to 25℃ ambient.

3.Testing Instrument(or equ) : L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.

4.Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40℃

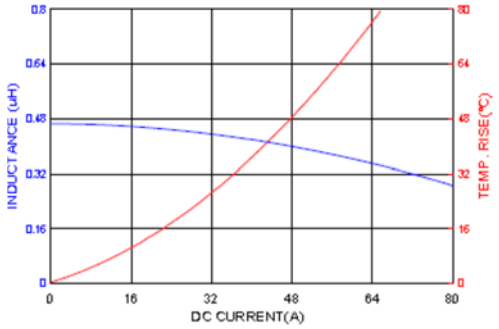
5.Saturation Current (Isat) will cause L0 to drop approximately 20%.

6.The part temperature (ambient + temp rise) should not exceed 125℃under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

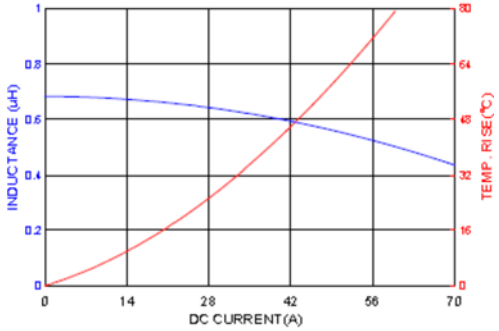
7.Special inquiries besides the above common used types can be met on your requirement.

TYPICALELECTRICALCHARACTERISTICS:

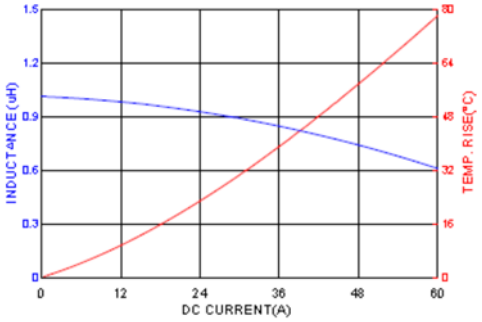
HMPL1205SP-R47



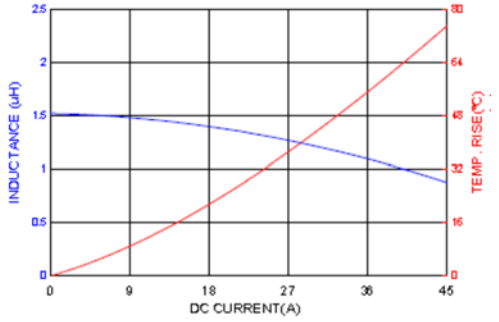
HMPL1205SP-R68



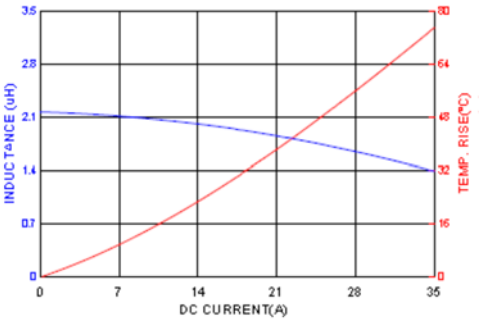
HMPL1205SP-1R0



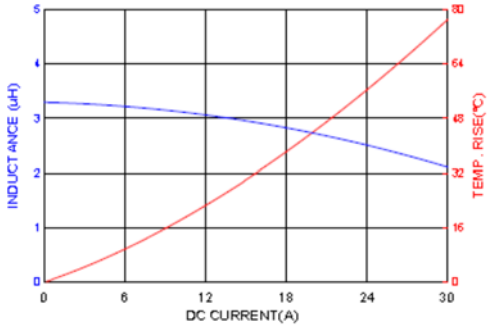
HMPL1205SP-1R5



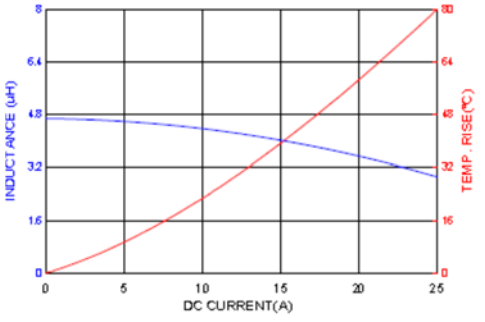
HMPL1205SP-2R2



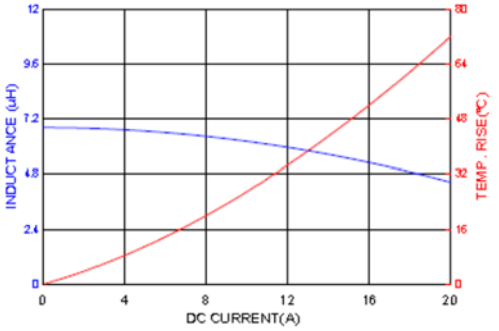
HMPL1205SP-3R3



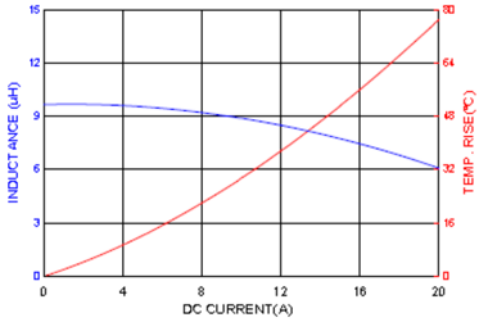
HMPL1205SP-4R7



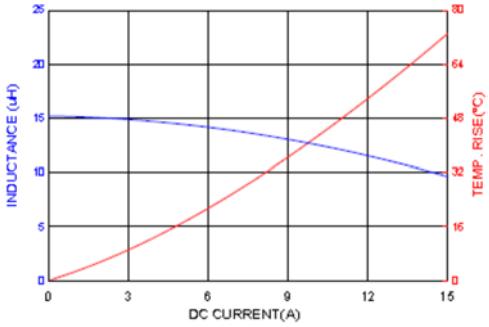
HMPL1205SP-6R8



HMPL1205SP-100

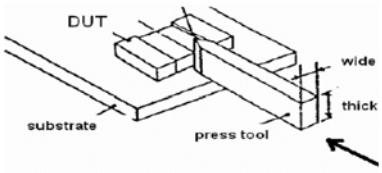


HMPL1205SP-150



Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	1. -10~+40℃,50~60%RH (Product with taping) 2. -40~+125℃(on board)	
Electrical Performance Test		
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.
DCR		CH16502,Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately△L30%	Saturation DC Current (Isat) will cause L0 to drop △L(%)
Heat Rated Current (Irms)	Approximately △T40℃	Heat Rated Current (Irms) will cause the coil temperature rise △T(℃). 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer
Reliability Test		
Life Test	Appearance：No damage. Inductance：within±10% of initial value Q：Shall not exceed the specification value. RDC：within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature： 125±2℃(Inductor) Applied current：rated current Duration：1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity：85±2 % R.H, Temperature：85℃±2℃ Duration：1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs,keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1：-40±2℃ 30±5min Step2：25±2℃ ≦0.5min Step3：125±2℃ 30±5min Number of cycles： 500 Measured at room temperature after placing for 24±2 hrs

<table>
<tr><td>Vibration</td><td></td><td>Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes
Equipment： Vibration checker
Total Amplitude:1.52mm±10%
Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)。</td></tr>
<tr><td>Bending</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
Inductance：within±10% of initial value
Q：Shall not exceed the specification value.
RDC：within ±15% of initial value and shall not exceed the specification value</td><td>Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm
<0805 inch(2012mm):40x100x0.8mm
Bending depth: >=0805 inch(2012mm):1.2mm
<0805 inch(2012mm):0.8mm
duration of 10 sec.</td></tr>
<tr><td>Shock</td><td>
<table>
<tr><th>Type</th><th>Peak value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr>
<tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
<tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr>
</table>
</td></tr>
<tr><td>Solder ability</td><td>More than 95% of the terminal electrode should be covered with solder。</td><td>Preheat: 150℃,60sec.。
Solder: Sn96.5% Ag3% Cu0.5%
Temperature: 245±5℃。
Flux for lead free: Rosin. 9.5%。
Dip time: 4±1sec。
Depth: completely cover the termination</td></tr>
<tr><td>Resistance to Soldering Heat</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
Inductance：within±10% of initial value
Q：Shall not exceed the specification value.
RDC：within ±15% of initial value and shall not exceed the specification value e</td><td>Depth: completely cover the termination
<table>
<tr><th>Temperature(°C)</th><th>Time(s)</th><th>Temperature ramp/immersion and emersion rate</th><th>Number of heat cycles</th></tr>
<tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr>
</table>
</td></tr>
<tr><td>Terminal Strength</td><td>Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles
With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.
 
</td></tr>
</table>

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.